

ABSTRACT

A method and system of cleaning to remove cutting dust and the like generated and adhering to a board material (1a) during drilling for electrical connection, and drying the board material, in a process of manufacturing a circuit board for small electronic equipment and the like. A large amount of board materials can be treated without receiving thermal damage by performing the steps of: placing sheets of the board material that have absorbed moisture resulting from cleaning, like a stack in a vacuum chamber (11); and drying the board material by repeating evacuation and pressurization under predetermined conditions while heating the board material.

WDC99 556210-1 043890 0560